

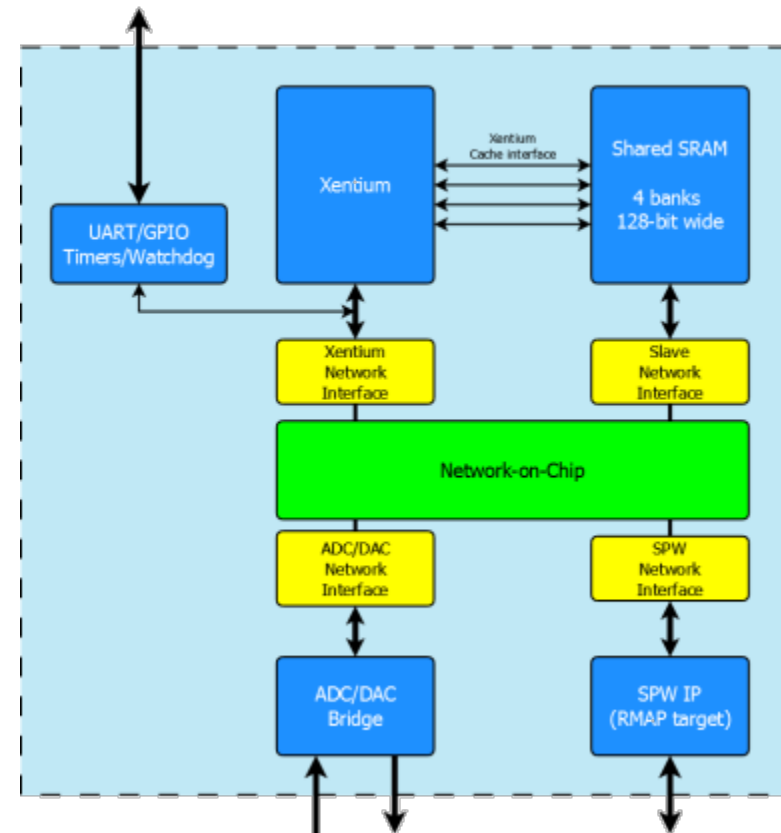
Step 2 – DARE+ / XentiumDARE

RAD.-HARD SILICON PROTOTYPE

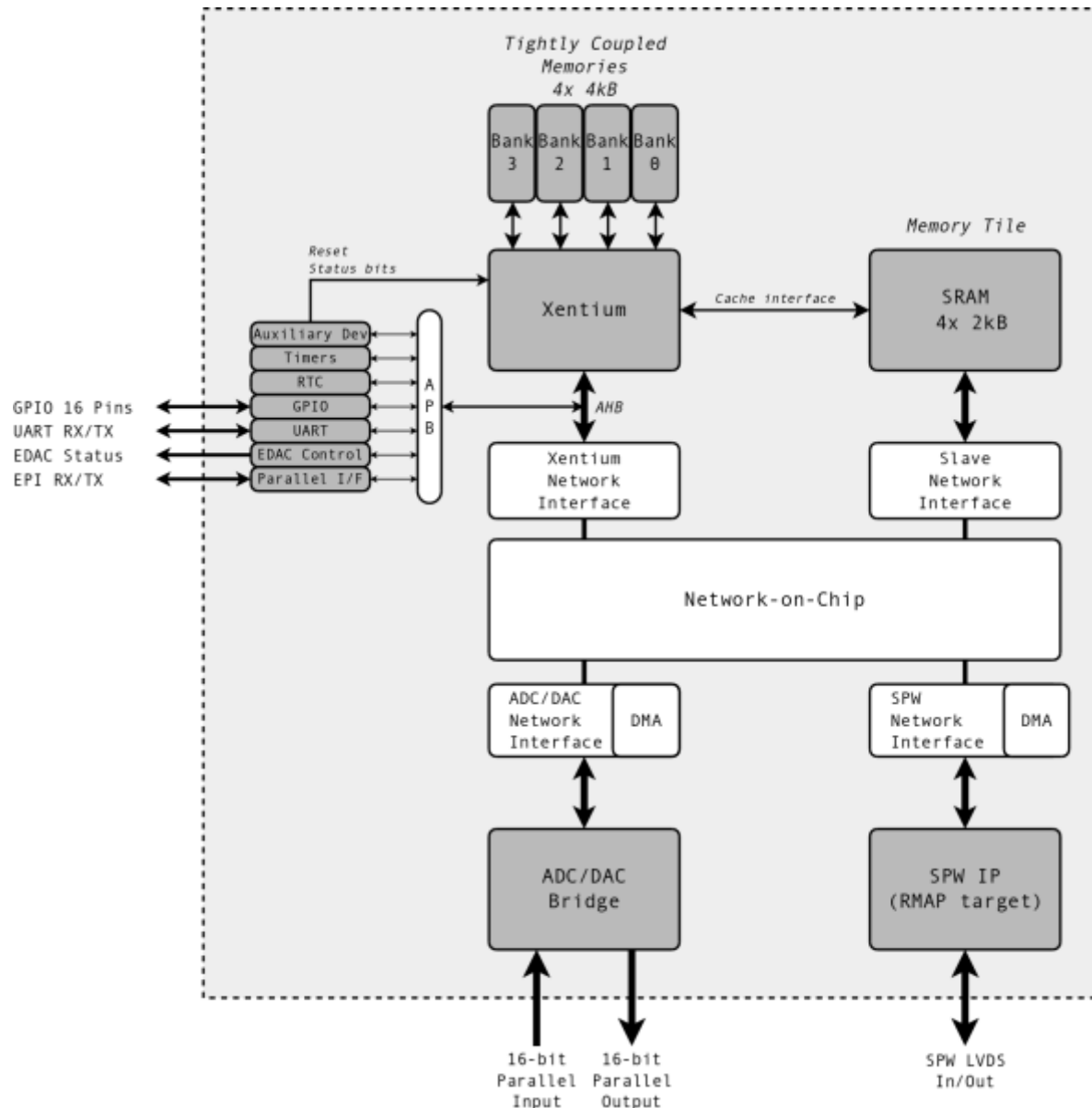
Rad.-hard DSP and NoC prototyping in DARE180

- n DARE+
 - n Rad.-hard prototyping of MPPB elements in DARE180
 - n ESA TRP activity, 2011 – 2013

- n ASIC Prototype
 - n DARE180 CMOS technology
 - n Available area: 5x10 mm²
 - n Architecture
 - n 1 Xentium core @100MHz
 - n Network-on-Chip
 - n SpW-RMAP interface
 - n Bridge interface to external ADC/DAC
 - n Small memory tile

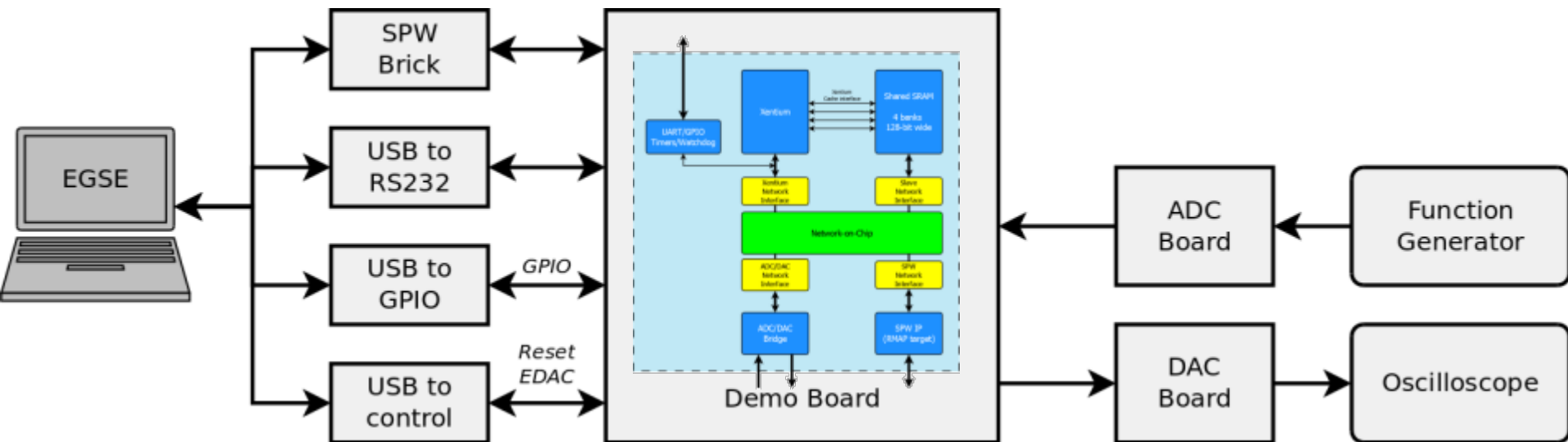


XentiumDARE Overview



- n Functional testing
 - n ESA NGDSP benchmarks

- n Radiation testing
 - n TID
 - n SEE - SEU / SET



Benchmark Environment



XentiumDARE

Functional radiation tests

- n Constraints:
 - n Limited time for each ion
 - n Functionality (no SPW)
- n Self-checking Xentium programs:
 - n Xentium + Memory Tile
 - n Xentium + Data banks
 - n Xentium + devices
 - n Xentium + ADC/DAC
 - n Xentium + SPW (front-end only)
- n Xentium Binary uploaded to ASIC
- n Results are output on the GPIOs

Benchmarks Introduction

- n Subset of “Next Generation Space DSP Software benchmarks”
- n Implemented 4 of 5 benchmarks
 - n Benchmark 1: I/O Performance
 - n Benchmark 2: Analog acquisition, processing and output
 - n Benchmark 4: Onboard Data Processing Case 1
 - n Benchmark 5: Onboard Data Processing Case 2
- n Operating conditions
 - n System frequency: 50 MHz*
 - n SpaceWire frequency: 200 MHz (transmit clock)
 - n Board power supply voltage: 1.95 V

* limited due to board issue; 100 MHz achievable

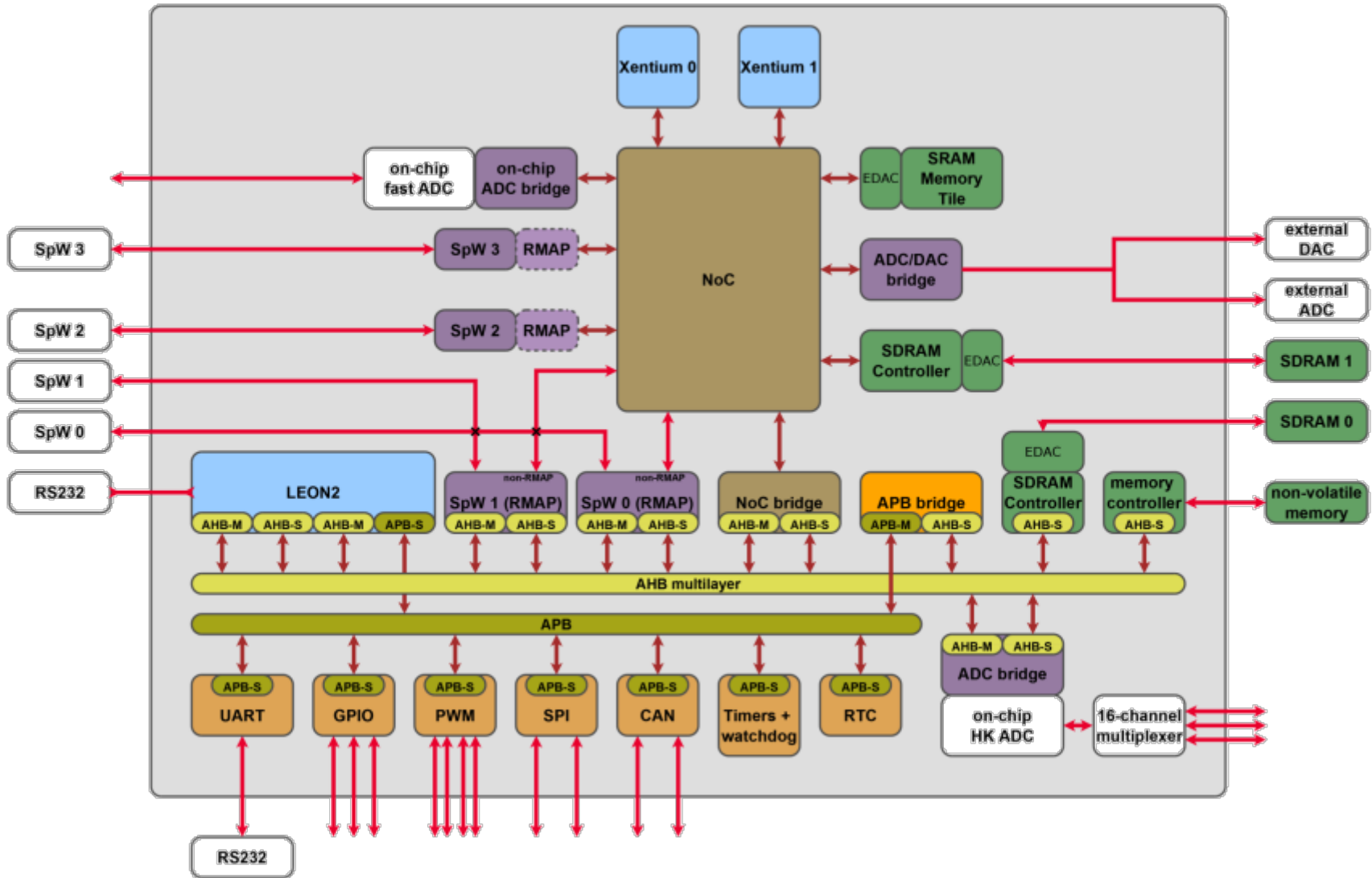
XentiumDARE Summary

- n Final review & public presentation in December 2014
- n XentiumDARE operational @100 MHz
- n Power consumption: Core 1.8V; IO 3.3V
 - n Dynamic <1.5W at full load
 - n Static < 5mW
- n Area
 - n 5x10 mm²
- n Radiation hardened (1 Mrad, LET < 70MeV/cm²/mg)
- n All benchmarks are functionally correct and pass
- n Performance @ 100 MHz system clock
 - n 400 MMAC/s (16-bit)
 - n 16-taps FIR @20 MSPS
 - n 1k-FFT @18 MSPS
 - n ADC/DAC @50 MSPS max
 - n SpaceWire @200 Mbit/s

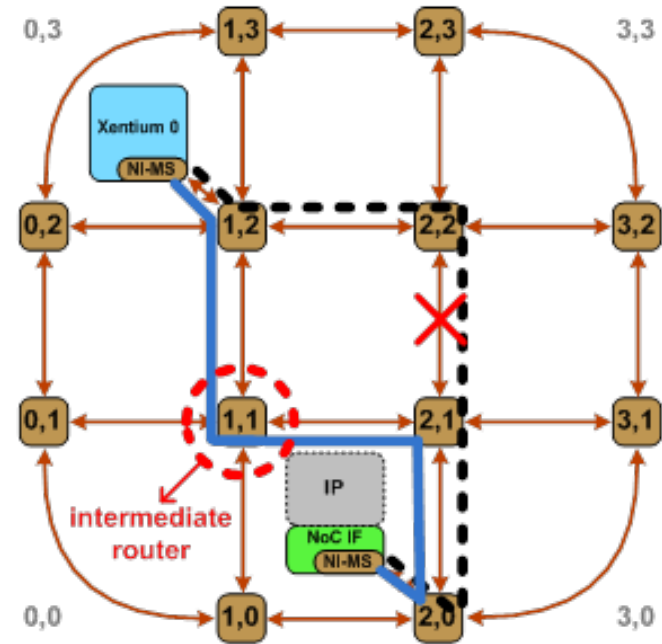
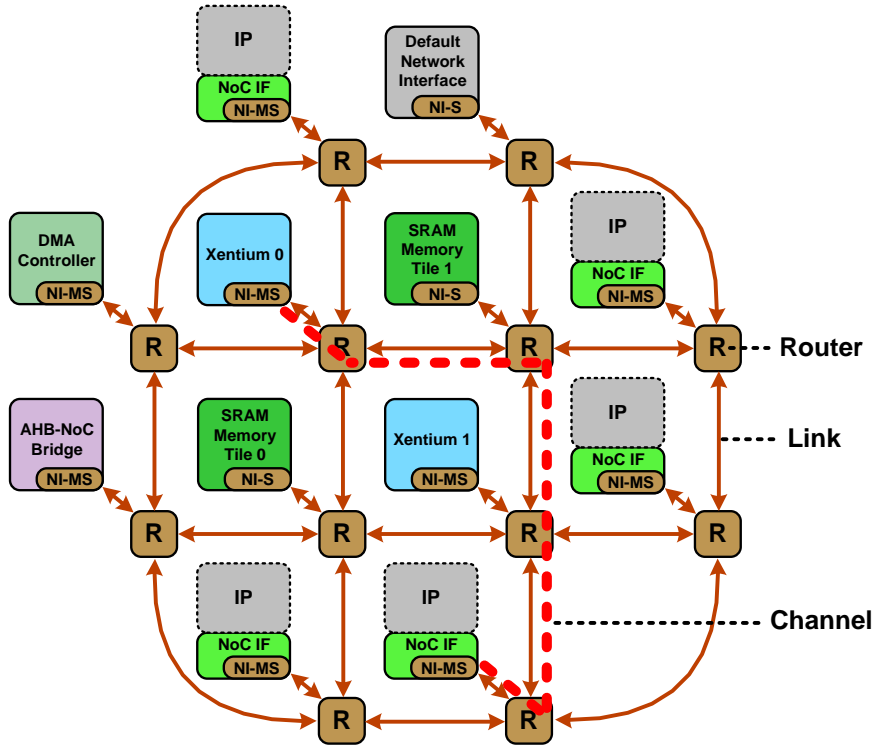
Step 3 – ASIC implementation

WHAT'S NEXT ...

Scalable Sensor Data Processor (draft architecture)



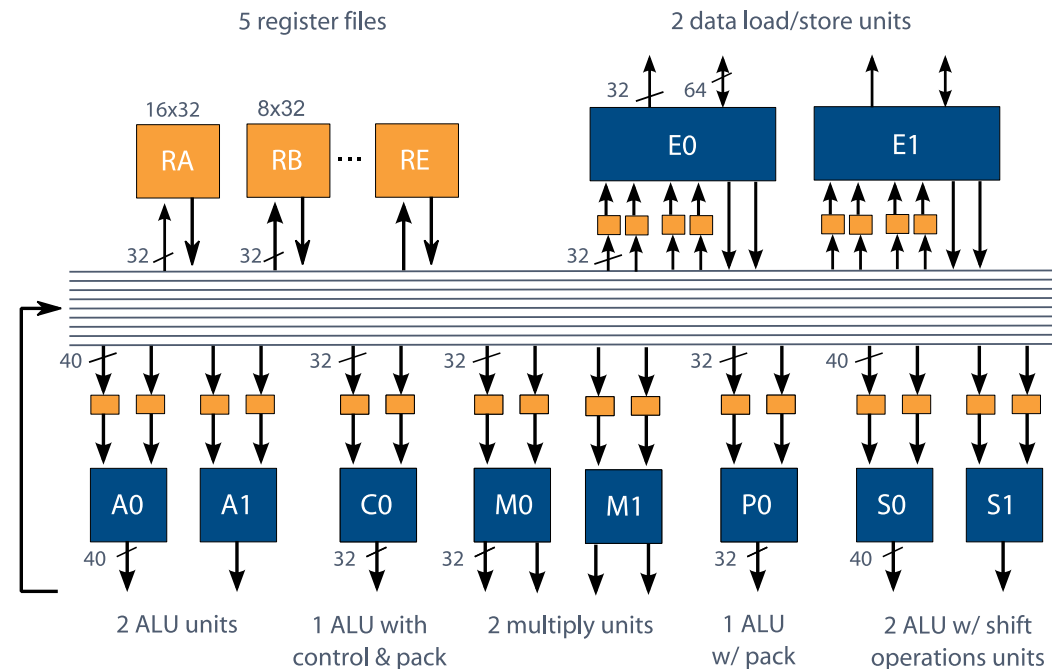
Reconfigurable XY routing



Work around (partly) faulty switches and links

Xentium architecture hardware extensions

- n Hardware floating-point support
- n Bit manipulation instructions
- n Hardware debug support



Many-Core DSP for Space 65nm - estimations

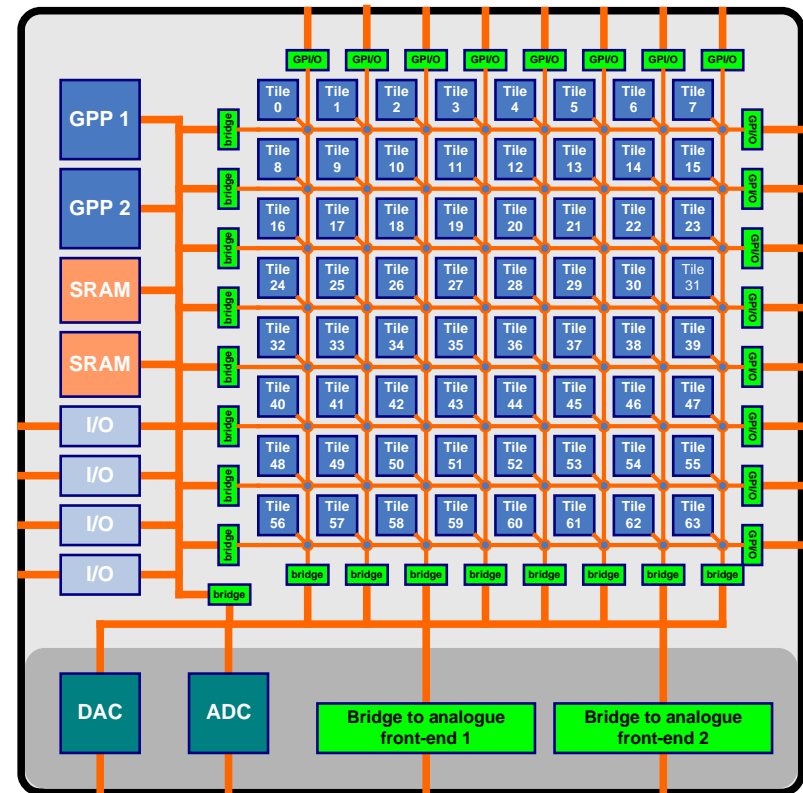
n Xentium VLIW DSP core in rad.-hard 65nm CMOS

- n Clock: 300 MHz
- n Performance: 1.2 GMACs/s
- n NoC per link: 9.6 Gbit/s
- n Area: 1.1 mm²
 - n 75% gates utilization
 - n Including NoC interface

n Many-core SoC example

- n 48 Xentium processing tiles
- n 16 memory tiles
- n 60 NoC routers
- n 8×8 mesh

à 60 Giga MAC operations/s



Summary

- n Multi-core DSP architecture is
 - n Heterogeneous and scalable
 - n Functionally evaluated on FPGA in MPPB
 - n Tested as rad.-hard ASIC prototype in XentiumDARE

- n Multi-core Xentium DSP sub-system IP
 - n Scalable processing power
 - n Scalable NoC-based interconnect
 - n Currently being integrated in Scalable Sensor Data Processor





Gerard Rauwerda, CTO & co-founder
Gerard.Rauwerda@recoresystems.com

Recore Systems BV
P.O. Box 77, 7500 AB,
Enschede, The Netherlands
+31 53 4753 000
7 +31 53 4753 009
info@recoresystems.com



RECORE

www.recoresystems.com